

## SUMMARY

An apparatus for connecting an integrated circuit to a support has a circuit board having a first surface for attaching the integrated circuit and a second surface opposite to the first surface. Recesses are provided in the second surface for receiving at least portions of solder balls for electrically and mechanically connecting the circuit board to the support. Solder pads are formed within the recesses. An IC BGA package making use of such an integrated circuit can be implemented with a reduced height and improved electrical characteristics when compared to existing designs.